

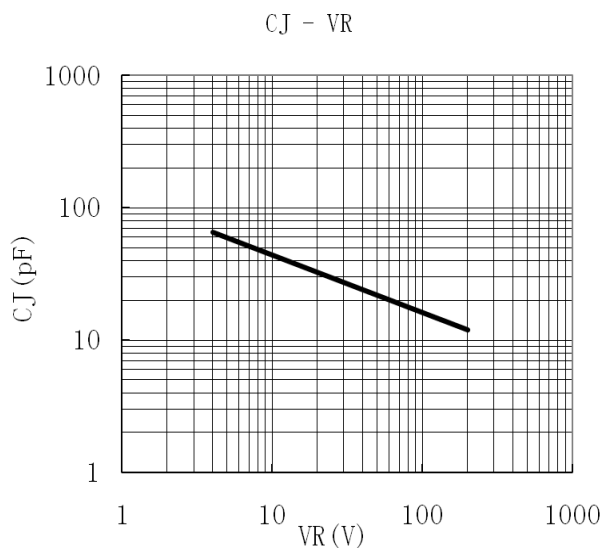
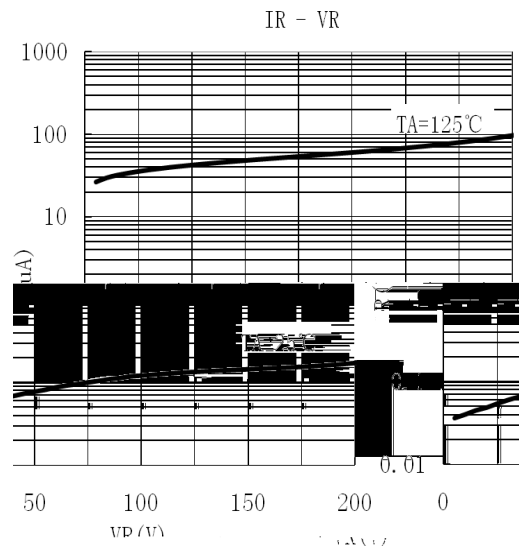
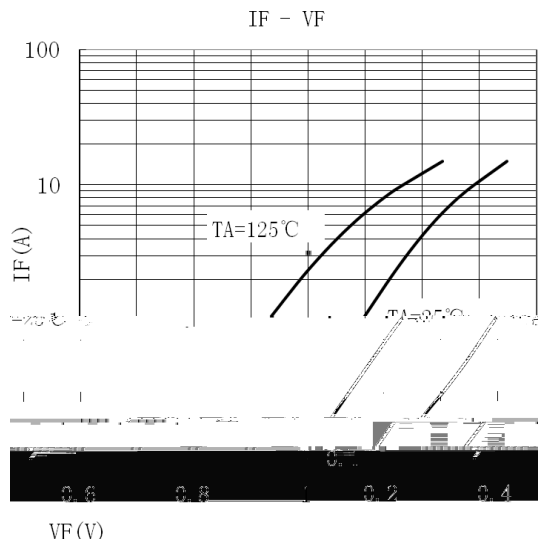
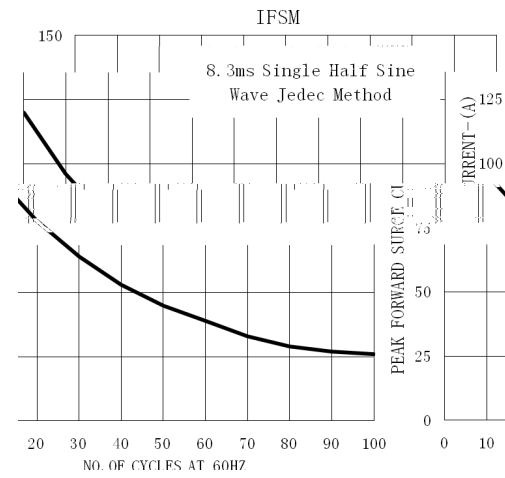
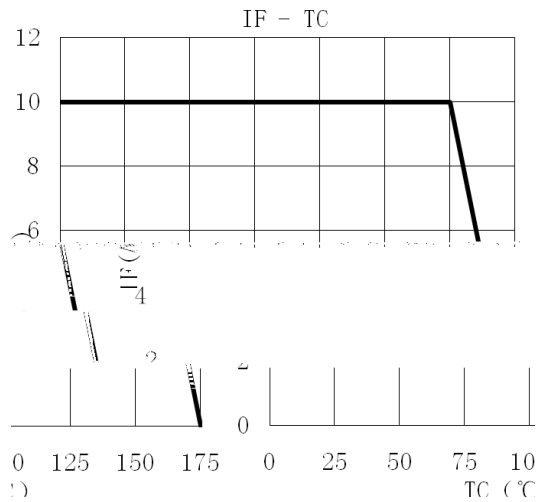
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
Average Rectified Forward Current	$I_{F(AV)}$	10	A
Peak Repetitive Forward Current	I_{FRM}	10	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current	I_{RRM}	0.5	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	2.5	/W
Junction and Storage Temperature Range	$T_j T_{stg}$	-65~150	

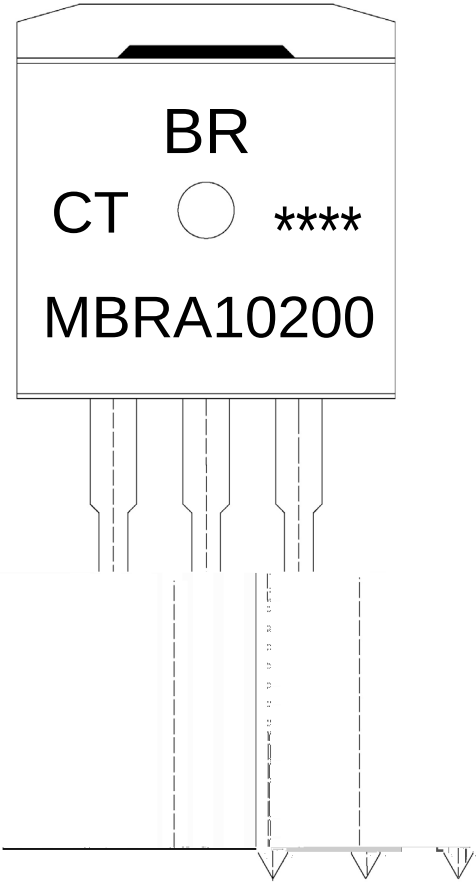
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_R		200			V
Forward Voltage	V_{FM}	$I_F=5.0A(T_C=25^{\circ}C)$			0.99	V
		$I_F=5.0A(T_C=125^{\circ}C)$			0.87	V
Instantaneous Reverse Current	I_{RM}	$V_R=200V(T_C=25^{\circ}C)$			0.15	mA
		$V_R=200V(T_C=125^{\circ}C)$			150	mA
Voltage Rate of Change	dv/dt				10000	V/ μ s

/ Electrical Characteristic Curve

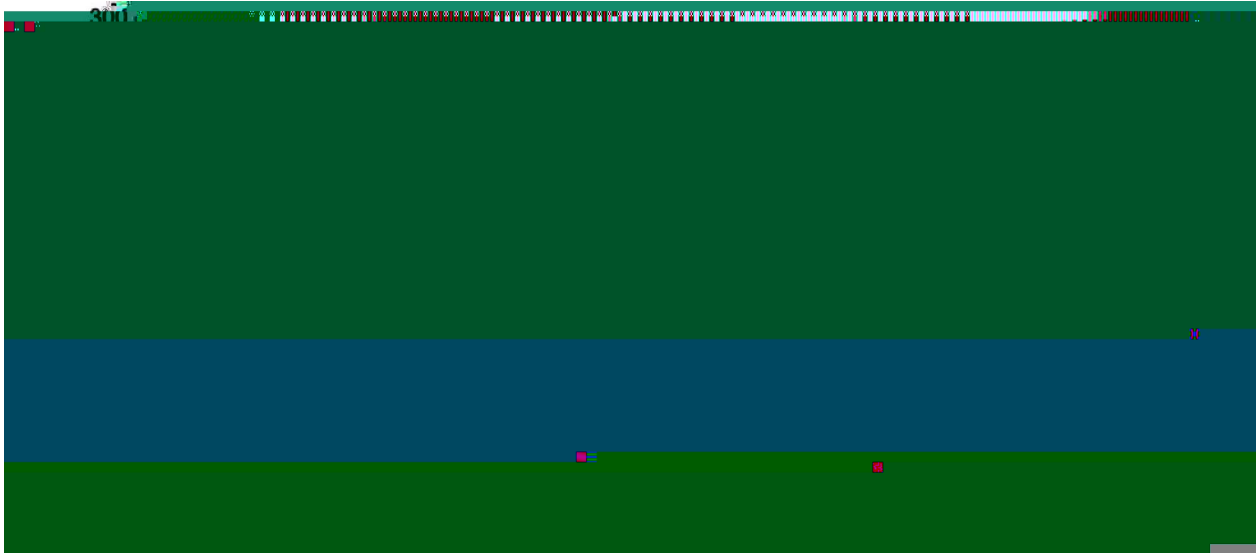


/ Marking Instructions



٢ " χ	
EU χ	ꠤ ٣ " ꠤ
P EUD43533 χ	ꠤ ٢ β ٣ N
FW:	ꠤ ٧ ٧ ꠤ =
---- χ	ꠤ ١ ٢ ꠤ N ꠤ ١ ٢ ꠤ N ψ ꠤ
Note:	
BR:	Company Code
MBRA10200 χ	Product Type.
CT:	Internal Structure
****:	Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



1. 预加热: 25~150 °C, 60~90sec;

2. 峰值温度: 255 ± 5 °C, 5 ± 0.5sec;

3. 冷却速度: 2~10 °C/sec.

Note:

1.Preheating:25~150 °C , Time:60~90sec.

2.Peak Temp.:255 °C ± 5 , Duration:5 °C ± 0.5sec.

3. Cooling Speed: 2~10 °C /sec.

/ Resistance to Soldering Heat Test Conditions

1. 温度: 270 ± 5 °C

2. 时间: 10 ± 1 sec.

Temp.:270±5

Time:10±1 sec

/ Packaging SPEC.

1. 包装形式: TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱

/ Notices